

CS99-3430

190 CotC

April 29, 2005

To: Commissioner of Patents
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Attn: Publishing Division
Certificate of Correction Branch

From: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subj: Serial No. 10/076,244 F/D 2/13/2002
Patent No. 6,821,888 Issued 11/23/04
Inventor: Yakub Aliyu, Simon Chooi, Mei Sheng Zhou, John Sudijono, Subhash
Gupta, Sudipto Ranendra Roy, Paul Ho, Yi Xu

REQUEST FOR CERTIFICATE OF CORRECTION

Dear Sir:

Pursuant to 37 C.F.R. 1.322, a Certificate of Correction is requested for the above identified issued US Patent.

Due to an Office mistake, the third, fourth and fifth inventor's name or residence were reproduced incorrectly on the cover sheet. The complete and correct names and residences for the three inventors are --Mei Sheng Zhou, Singapore (SG), John Sudijono, Singapore (SG) and Subhash Gupta, Singapore (SG)--. It is clear the mistake was made

by the Office because the inventor's name and residences were correct on the Corrected Filing Receipt and the Declaration papers.

Copies of the Forms are attached.

Form PTO-1050 has been completed, as required by MPEP S1485, indicating the corrections to the three inventors names and residences. No fee is included since this error was due to an Office mistake. Please issue the Certificate of Correction to correct this error.

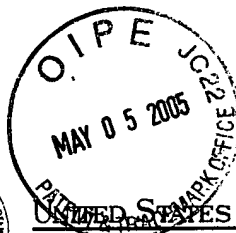
If there are any questions, please contact the undersigned attorney at (845) 453-5863. Thank you for your attention to this matter.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'SBA', is written over the printed name.

Stephen B. Ackerman, Reg. No, 37,761

SEP 27 2000



UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/612,576	07/07/2000	2812	690	CS99-343	3	17	3

George O Saile
20 McIntosh Drive
Poughkeepsie, NY 12603

CORRECTED FILING RECEIPT

OC00000005412758

Date Mailed: 09/20/2000

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).**

Applicant(s)

Simon Chooi, Singapore, SINGAPORE;
Yakub Aliyu, Singapore, SINGAPORE;
Mei Sheng Zhou, Singaopre, SINGAPORE;
John Sudijono, Singapore, SINGAPORE;
Subhash Gupta, Singapore, SINGAPORE;
Sudipto Ranendra Roy, Singapore, SINGAPORE;
Paul Ho, Singapore, SINGAPORE;
Yi Xu, Singapore, SINGAPORE;

Continuing Data as Claimed by Applicant**Foreign Applications**

If Required, Foreign Filing License Granted 08/25/2000

Title

Method of copper/copper surface bonding using a conducting polymer for application in IC chip bonding

Preliminary Class

438

DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

DOCKET NO. CS99-343

As a below named Inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled
A Method Of Copper/Copper Surface Bonding Using A Conducting Polymer For Application In IC Chip Bonding

the specification of which (check one)

X is attached hereto.

was filed on _____

Application Serial No. _____

and was amended on _____

(if applicable)

I hereby state that I have reviewed and understand the contents of the above Identified specification including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed:

(Number)	(Country)	(Day/Month/Year Filed)
(Number)	(Country)	(Day/Month/Year Filed)

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>09/612,576</u>	<u>7/7/00</u>	<u>PENDING</u>
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name & registration no.)

GEORGE O. SAILE. (Reg. No. 19,572), STEPHEN B. ACKERMAN (Reg. No. 37,761)

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Direct telephone Calls to: (name & telephone number) GEORGE O. SAILE NEW YORK 914 452 5863

Full name of sole or first inventor

YAKUB ALIYU02/07/07
Date

Inventor's signature

Residence 100 Cashew Crescent, Singapore 679831 SingaporeCitizenship BritishPost Office Address 60 Woodlands Ind. Park D, St. 2, Singapore 738406 SingaporeDOCKET NO. CS99-343

SIMON SHOOT

Full name of second inventor

Date

Inventor's signature

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Singapore citizen

Citizenship

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Post Office Address

MEI SHENG ZHOU

Full name of third inventor

Date

Inventor's signature

23 Nov 2000

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Citizenship

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Post Office Address

JOHN SUDIJONO

Full name of fourth inventor

Date

Inventor's signature

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SUBHASH GUPTA

Full name of fifth inventor

Date

Inventor's signature

23.11.2000

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Citizenship

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Post Office Address

SUDIPTO RANENDRA ROY

Full name of sixth inventor

Date

Inventor's signature

29.11.2000

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Residence

U.S.A.

Citizenship

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Post Office Address

DUPLICATE

PTO/SB/44 (02-01)

Approved for use through 01/31/2004. OMB 0651-0033

U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

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(Also Form PTO-1050)

**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

PATENT NO : US 6,821,888

DATED : 11/23/04

INVENTOR(S) : Yakub Aliyu, Simon Chooi, Mei-Sheng Zhou, John Sudijono, Subhash Gupta, Sudipto Ranendra Roy

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page, in item (75), delete "Meisheng Zhou, Singapore (SG)" and replace with --Mei Sheng Zhou, Singapore (SG)--, delete "John Sudijono, S'pore (SG)" and replace with --John Sudijono, Singapore (SG)-- and delete "Subhash Gupta, S'pore (SG)" and replace with --Subhash Gupta, Singapore (SG)--.

MAILING ADDRESS OF SENDER:

George O. Saile & Associates
20 McIntosh Drive
Poughkeepsie, NY 12603

PATENT NO. US 6,821,888

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Burden Hour Statement: This form is estimated to take 1.0 hour to complete. Time will vary depending upon the needs of the individual case. Any comment on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

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